## The Latest Progress in Model-Based Mask Data Preparation

Linyong (Leo) Pang Bo Su D<sub>2</sub>S, Inc.

L. Pang, The Latest Progress in Model-based Mask Data Preparation

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# **eBeam Needs Proximity Correction**



- At 20nm node, eBeam writing is no longer "faithful"
- Needs proximity correction, like OPC at 90/65nm
- Dose margin is the problem

# < 50nm, Context is Critical





# < 50nm, Context is Critical





#### Pictures enlarged to show contour

## **Model-Based MDP is the Answer**

D<sub>2</sub>S

- Above 50nm, context-independent, rules-based processing works well enough
- Below 50nm, context is critical
- If we can't push below 40nm, we leave the benefits of Moore's Law on the table
- Simulation-based mask processing is the answer



# D<sub>2</sub>S TrueModel is Reaching 1.5nm RMS, Qualified at World Leading Semi Companies





# MB-MDP Has Right Approaches for both OPC and ILT Masks



# OPCS2 = MPC+ Dose Modulation + Conventional MDP







# **ILT Adopted as the Way Forward**

ILT expertise proliferated





2014 panel

# Complex Masks Pose Challenges, in Particularly, Mask Writing







### Long VSB write-times

# Low accuracy due to proximity effect

# **Overlapping Shots = Reduced Shot Count**





- = Better process margin
- = Better CDU
- = No mask-write time vs. mask-quality compromise

# MB-MDP, Overlapped Shots Required with VSB $D_{2S}$ for Complex Masks

- Conventional solution:
  - Geometry-based
  - Shots cover CAD layout without overlapping
  - More shot count and worse mask fidelity
- D<sub>2</sub>S solution:
  - Model-based, better CDU control
  - Utilizes overlapping shots to maximize shot contribution to the final mask shapes
  - Less shot count and better mask fidelity



### **Complex Shapes are only Feasible with MB-MDP and Overlapped Shots**



# Benefits of MB-MDP Proven at Key Customer Sites





# ~50% CDU Improvement on 7nm OPC Mask using MB-MDP OPCS2





# Is MB-MDP Run Time Ready for Production Use?

- Over 100X more computation than MB-OPC
- Mask scale 4X of wafer scale
  - Imagine calculation on every 1nm on wafer scale
- Requires optimization on fracturing
  Break the OPC pattern into shots
- Has to consider overlapped shots
- eBeam proximity effect has short (nm), mid, and long range (mm)

# **Scientific Computing Is Moving to GPU**



Jen-Hsun Huang, CEO of NVIDIA, GPU Technology Conference, 2015



# D<sub>2</sub>S 400TFLOPS CDP Using GPUs Is In Production Use at Mask Shops



- 400 TFLOPS
- Simulates the entire mask plane
- All standard parts, with built-in redundancy
- 10<sup>th</sup> CDP being Installed this month



#### **MB-MDP** Run Time Improvement



# Multi-Beam Mask Writer Will Need Simulation-Based Processing Even More

- Multi-beam mask writer is the ultimate answer for ILT
  - Write-time independent of mask complexity
  - Use slower resist
    - Smaller features
- It requires MB-MDP
  - Large data set to process
  - Needs dose modulation



H. Matsumoto, 2016 Introduction and recent results of Multi-beam mask writer MBM-1000, SPIE 2016 eBeam Initiative Luncheon Event

# **MB-MDP** is Being Deployed in Production



- ILT is being deployed in production at the leading edge. Mask makers are faced with ILT masks
- Overlapped shots and MB-MDP enable VSB mask writer to write complex ILT masks
- GPU-accelerated MB-MDP can meet the speed requirement of mass production
- MB-MDP is being deployed in production for both OPC and ILT masks
- Multi-beam mask writer will require MB-MDP, too

